SYSTEM AND METHOD FOR PULSE CURRENT PLATING

ABSTRACT OF THE DISCLOSURE

According to one embodiment of the present invention, a method for electroplating electronic devices is disclosed which includes placing the outer surface of a substrate in contact with a solution comprising a conductive material. An electrical current is passed through the solution and the substrate so as to cause the conductive material to deposit on the substrate under the electromotive force caused by the electrical current. The level of the electrical current is varied from a first current level to a second current level to provide for differing rates of deposition of the conductive material on the substrate. The second current level provides a relaxation period to allow the conductive material deposited on the substrate to come to equilibrium.